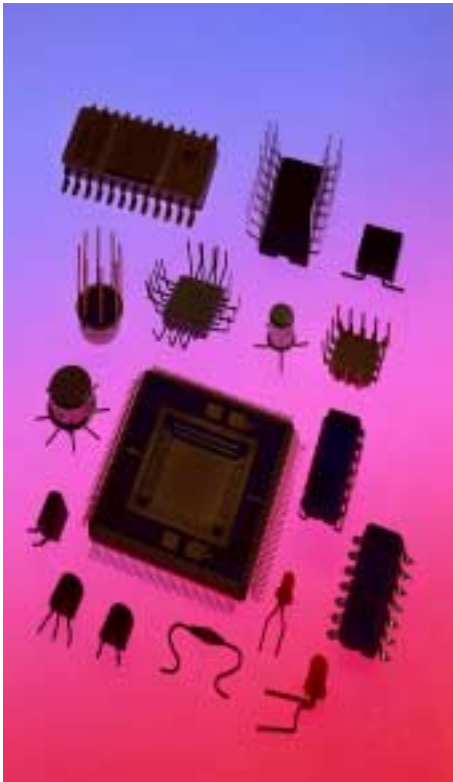


SMT LEAD FORM & TRIM

Solutions

Component Preparation Services

Lead Forming....Tinning....Leak Testing



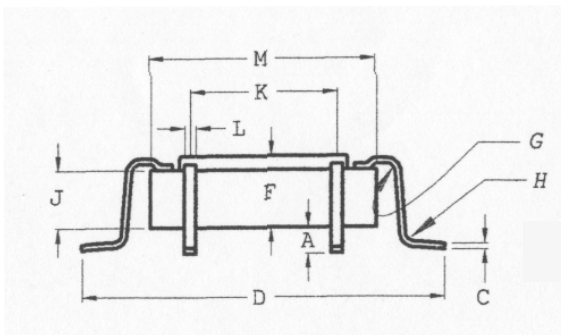
Fancort is the industry leader in component lead preparation services for the Semiconductor and Aerospace industries. We have over thirty years of experience in lead forming of a wide variety of packages including large and small flatpacks and quadpacks, DIPs, fiber optic headers and devices that require conversion from through-hole to SMT. We use our unique universal and dedicated tooling systems and complete process control to ensure accuracy and quick turnaround of your parts to Jeduc and/or mil-spec dimensions with optional services such as leak testing and tinning, if required.

FEATURES

- Lead forming to Mil-std 883E and NASA std FP 51 3414 Rev. H Section 3
- Complete process control and documentation
- Standard footprint layouts available or we will design your custom footprint
- All work done in a controlled ESD Safe environment
- Turnaround can be as little as three days; typically 10 workdays
- Inspection of incoming devices for lead skew or other deformity
- Inspection Report and Certificate of Compliance

OPTIONS

- Lead tinning to Mil-std and NASA std 8739.2 8199 "workmanship std. for SMT" and Mil 2003.7
- Solder used is 63/37 standard with no clean flux
- Expedited delivery available
- Adjustable matrix trays for return shipping of your devices, including tray for Pick and Place machinery, and new single tray for holding 1 QFP or FP
- Lead form and trim tooling available for purchase to reduce costs on long-running jobs
- Leak testing to Mil-std 883, Med + Mod 1014.10, conditions A & C fine and gross
- Contractual agreements



COST

Setup charge and piece price depending on quantity and service required